



A Product Line of Diodes Incorporated



ZXMN10A11K

100V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C		
100V	350mΩ @ VGs = 10V	3.5A		
	450mΩ @ Vgs = 6V	3.1A		

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- DC-DC Converters
- Power management functions
- Uninterrupted power supply

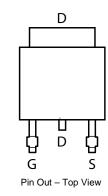
Features and Benefits

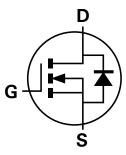
- Fast switching speed
- Low input capacitance
- "Green" Component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TO252-3L
- Case Material: Molded Plastic "Green" Molding Compound, UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.33 grams (approximate)







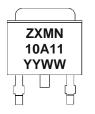
Equivalent Circuit

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN10A11KTC	See Below	13	16	2,500

Note: 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



ZXMN = Product Type Marking Code, Line 1 10A11 = Product Type Marking Code, Line 2 YYWW = Date Code Marking YY = Year (ex: 09 = 2009) WW = Week (01-52)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V _{DSS}	100	V	
Gate-Source voltage			V _{GS}	±20	V	
Continuous Drain current	V _{GS} = 10V	(Note 3) T _A = 70°C (Note 3) (Note 2)	ID	3.5 2.8 2.4	А	
ulsed Drain current V _{GS} = 10V (Note 4)		(Note 4)	IDM	9.9	А	
Continuous Source current (Body diode) (Note 3)		Is	8.4	А		
Pulsed Source current (Body diode) (Note 4)		I _{SM}	9.9	А		

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
	(Note 2)		4.06 32.4		
Power dissipation Linear derating factor	(Note 3)	P _D	8.5 68.0	W mW/°C	
	(Note 6)		2.11 16.8		
	(Note 2)		30.8	°C/W	
Thermal Resistance, Junction to Ambient	(Note 3)	R ₀ JA	14.7		
	(Note 6)		59.1		
Thermal Resistance, Junction to Lead	(Note 5)	$R_{\theta JL}$	1.10	°C/W	
Operating and storage temperature range	TJ, TSTG	-55 to 150	٥°		

Notes: 2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

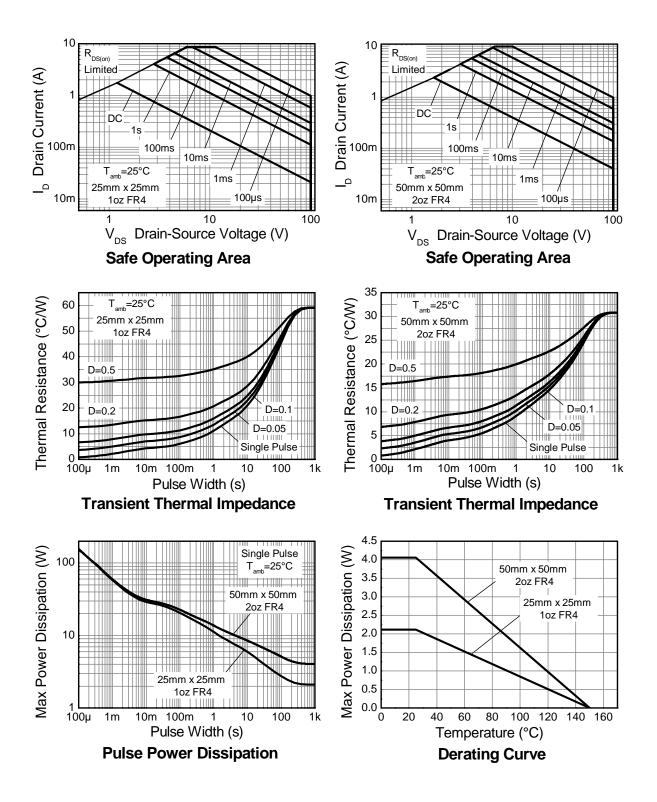
3. Same as note 2, except the device is measured at t \leq 10 sec.

4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature. 5. Thermal resistance from junction to solder-point (at the end of the drain lead).

6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with the high coverage single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.



Thermal Characteristics





Electrical Characteristics @T_A = 25°C unless otherwise specified Characteristic Symbol Max Unit **Test Condition** Min Тур OFF CHARACTERISTICS **BV**_{DSS} 100 V Drain-Source Breakdown Voltage $I_D = 250 \mu A, V_{GS} = 0V$ Zero Gate Voltage Drain Current 1 μΑ $V_{DS} = 100V, V_{GS} = 0V$ IDSS ____ ____ Gate-Source Leakage Igss ____ ± 100 nA $V_{GS} = \pm 20V, V_{DS} = 0V$ **ON CHARACTERISTICS** Gate Threshold Voltage VGS(th) 2 4 V $I_D = 250 \mu A$, $V_{DS} = V_{GS}$ ____ 0.350 $V_{GS} = 10V, I_D = 2.6A$ Static Drain-Source On-Resistance (Note 7) R_{DS} (ON) Ω 0.450 $V_{GS} = 6V, I_D = 1.3A$ 4 S $V_{DS} = 15V, I_D = 2.6A$ Forward Transconductance (Notes 7 & 8) **g**fs V Diode Forward Voltage (Note 7) 0.850 0.950 I_S = 1.85A, V_{GS} = 0V V_{SD} Reverse recovery time (Note 8) 26 ns trr $I_{S} = 1.0A$, di/dt = 100A/µs Reverse recovery charge (Note 8) 30 nC Qrr DYNAMIC CHARACTERISTICS (Note 8) C_{iss} Input Capacitance 274 pF $V_{DS} = 50V, V_{GS} = 0V$ Output Capacitance 21 Coss pF ____ ____ f = 1MHzReverse Transfer Capacitance 11 pF Crss ____ ____ Total Gate Charge (Note 9) 3.5 nC Qq ____ ____ $V_{GS} = 6V$ Total Gate Charge (Note 9) 5.4 nC $V_{DS} = 50V$, Qg Gate-Source Charge (Note 9) 1.4 nC $I_{D} = 2.5A$ Q_{gs} $V_{GS} = 10V$ Q_{gd} Gate-Drain Charge (Note 9) 1.5 nC ____ Turn-On Delay Time (Note 9) 2.7 ns t_{D(on)} Turn-On Rise Time (Note 9) 1.7 ns $V_{DD} = 50V, V_{GS} = 10V$ tr Turn-Off Delay Time (Note 9) 7.4 $I_D = 1.0A, R_G \cong 6\Omega$ ns t_{D(off)} Turn-Off Fall Time (Note 9) 3.5 ns tf

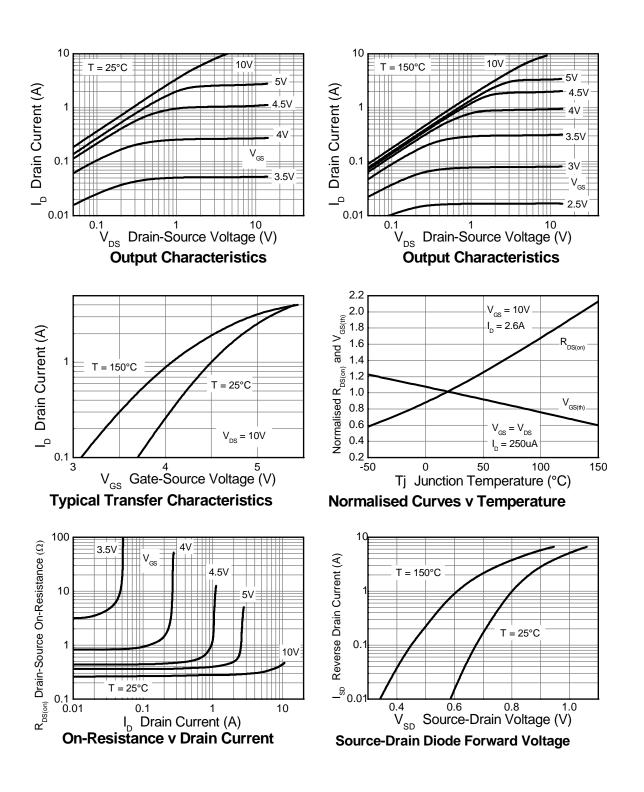
Notes: 7. Measured under pulsed conditions. Pulse width \leq 300µs; duty cycle \leq 2%

8. For design aid only, not subject to production testing.

9. Switching characteristics are independent of operating junction temperatures.

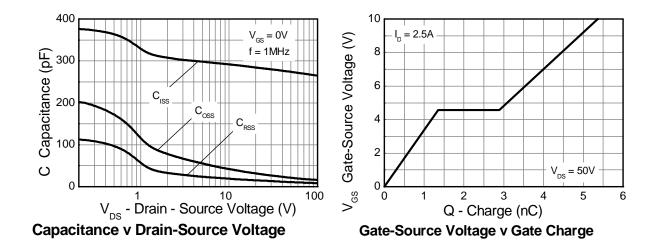


Typical Characteristics

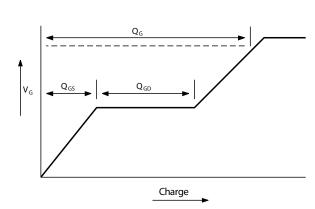




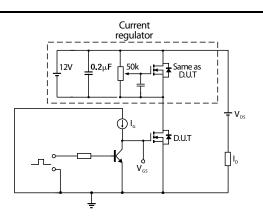
Typical Characteristics - continued



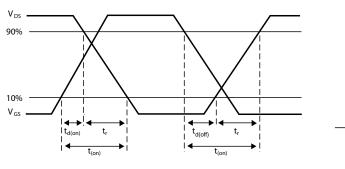
Test Circuits



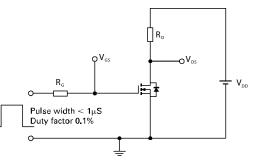
Basic gate charge waveform



Gate charge test circuit



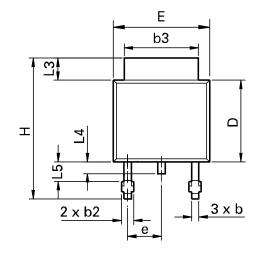
Switching time waveforms

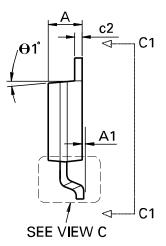


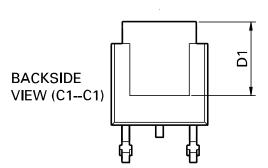
Switching time test circuit

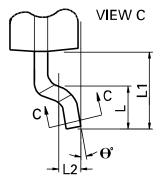


Package Outline Dimensions





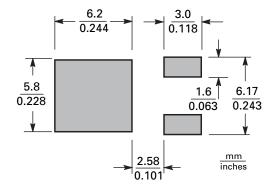




DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
А	0.086	0.094	2.18	2.39	е	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	н	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
с	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ1°	0°	10°	0°	10°
Е	0.250	0.265	6.35	6.73	θ°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-



Suggested Pad Layout



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